

NO PATTERN AREA

 NO CIRCUIT AREA

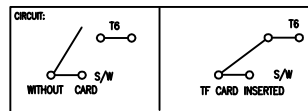
 SOLDER AREA

P.C.B LAYOUT
(TOLERANCE±0.05)

SIM pin assignment	
	Name
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

TF CARD PIN ASSIGNMENT

PIN NO.	PIN ASSIGNMENT
T1	DAT2
T2	CD/DAT3 ²
T3	CMD
T4	VDD
T5	CLK
T6	VSS
T7	DAT0
T8	DAT1



NOTE:

一. 材质及电镀方式 (MATERIAL AND FINISH)

- 塑胶 (HOUSING): LCP, UL 94V-0, COLOR: BLACK
- 端子 (CONTACT): COPPER ALLOY, GOLD FLASH PLATING ON CONTACT AREA, GOLD FLASH PLATING ON SOLDER TAILS, 50u" NICKEL UNDER PLATING OVER ALL
- 铁壳 (SHELL): SUS304-3/4H, 40u" NICKEL UNDER PLATING OVER ALL

二. 机械特性 (MECHANICAL CHARACTERISTICS)

- 插入力 (Insertion Force): 2.0Kgf Max
- 拔出力 (Withdrawal Force): 0.1Kgf Min
- 耐久性 (Durability): 5000次

三. 电气特性

- 额定电流 (Current rating): 1.0A AC/DC
- 接触电阻 (Contact resistance): 100mΩ MAX
- 绝缘电阻 (Insulation resistance): 500MΩ MIN
- 适用温度 (Operating temperature): -20°C ~ 65°C



深圳市华宇创精密电子有限公司

TOLERANCE: XX ±0.30 XXX ±0.25 XXXX ±0.15 X* ±2° X.X* ±0.5°	DRAWN BY: 陈一鸣	DATE: 2014-02-23	PART NAME: MICRO SIM+TF 二合一卡座 H2.3全贴	
	CHECKED BY: 马跃	DATE: 2014-02-23	PART NO.: HYCW68-21N117-230B	MOLD NO.:
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE: 2014-02-23	DRAW NO.: HYC-2109020951	SHEET NO.: 1 OF 1